

# LC03-6

## Low Capacitance Array for Surge & ESD Protection

TVS diodes are ideal for use as board level protection of sensitive semiconductor components. The LC03-6 combines a TVS diode with a rectifier bridge to provide transient protection in both common and differential mode with a single device. The capacitance of the device is minimized (< 25pF) to ensure correct signal transmission on high speed lines. The LC03-6 meets the short-haul (intra-building) transient immunity requirements of Bellcore1089 for telecommunications applications.

The LC03-6 has been specifically designed to protect sensitive components which are connected to high-speed data and transmission lines from overvoltage caused by ESD(electrostatic discharge), CDE (Cable Discharge Events),and EFT (electrical fast transients).

### Features

- Protects two I/O lines
- 2000 watts peak pulse power (tp = 8/20µs)
- Low capacitance
- Working voltages : 6V
- Low capacitance (<25pF) for high-speed interfaces
- Integrated structure saves board space and increases reliability
- Solid-state silicon avalanche technology
- Meets MSL 1 Requirements
- ROHS compliant
- WeiPan technology

### Main applications

- T1/E1 Line Cards
- T3/E3 and DS3 Interfaces
- STS-1 Interfaces
- ISDN S/T-Interfaces
- ISDN U-Interfaces
- 10/100 Ethernet

### Protection solution to meet

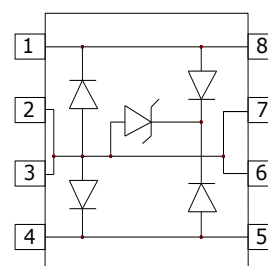
- Bellcore1089 (Intra-Building) 100A (2/10µs)
- ITU K.20 IPP=40A (5/310µs)
- IEC 61000-4-2 (ESD) ±15kV (air), ±8kV (contact)
- IEC 61000-4-4 (EFT) 40A (5/50ns)
- IEC 61000-4-5 (Lightning) 100A (8/20µs)

### Ordering Information

Device	Qty per Reel	Reel Size
WPLC03-6	2500	13 Inch



**SOP-8**



**Maximum ratings (Tamb=25°C Unless Otherwise Specified)**

Parameter	Symbol	Value	Unit
Peak Pulse Power (tp=8/20µs waveform)	P <sub>PPP</sub>	2000	Watts
Peak Pulse Current(tp=8/20µs waveform)	I <sub>PP</sub>	100	A
ESD Rating per IEC61000-4-2:	Contact	8	KV
	Air	15	
Lead Soldering Temperature	T <sub>L</sub>	260 (10 sec.)	°C
Operating Temperature Range	T <sub>J</sub>	-55 ~ 150	°C
Storage Temperature Range	T <sub>STG</sub>	-55 ~ 150	°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

\*Other voltages may be available upon request.

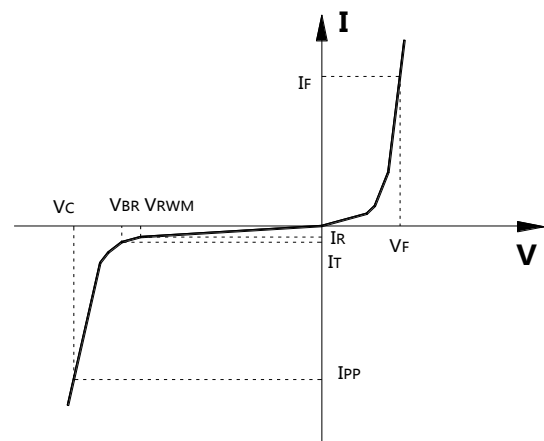
1. Non-repetitive current pulse, per Figure 1.

**Electrical characteristics (Tamb=25°C Unless Otherwise Specified)**

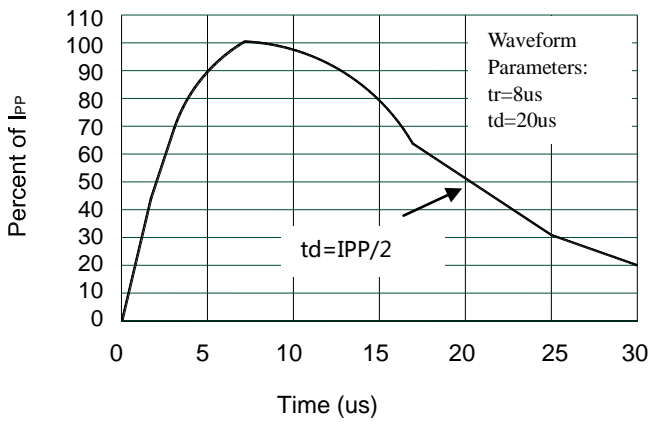
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
V <sub>RWM</sub>	Reverse Working Voltage	Line to Ground			6	V
V <sub>BR</sub>	Reverse Breakdown Voltage	I <sub>T</sub> = 1mA, Line to Ground	6.0			V
I <sub>R</sub>	Reverse Leakage Current	V <sub>RWM</sub> = 6V, Line to Ground			25	µA
V <sub>C</sub>	Clamping Voltage	I <sub>PP</sub> = 50A, tp =8/20µs, Line to Ground			20	V
		I <sub>PP</sub> = 100A, tp =8/20µs, Line to Ground			28	V
I <sub>PP</sub>	Peak Pulse Current	tp =8/20µs			100	A
C <sub>J</sub>	Junction Capacitance	V <sub>R</sub> = 0V, f = 1MHz, between I/O pins		8	12	pF
		V <sub>R</sub> = 0V, f = 1MHz, any I/O pin to Ground		16	25	pF

Junction capacitance is measured in VR=0V,F=1MHz

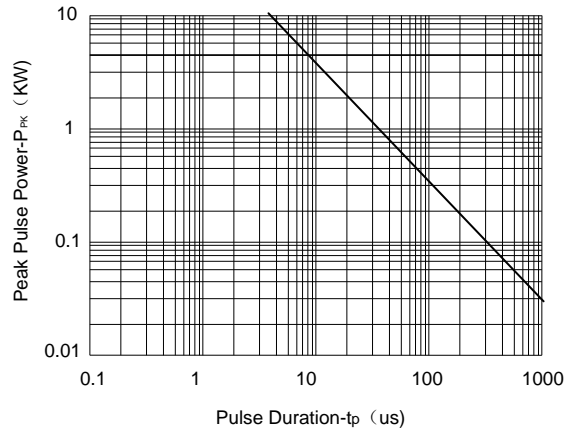
Symbol	Parameter
V <sub>RWM</sub>	Working Peak Reverse Voltage
V <sub>BR</sub>	Breakdown Voltage @ I <sub>T</sub>
V <sub>C</sub>	Clamping Voltage @ I <sub>PP</sub>
I <sub>T</sub>	Test Current
I <sub>RM</sub>	Leakage current at V <sub>RWM</sub>
I <sub>PP</sub>	Peak pulse current
C <sub>O</sub>	Off-state Capacitance
C <sub>J</sub>	Junction Capacitance



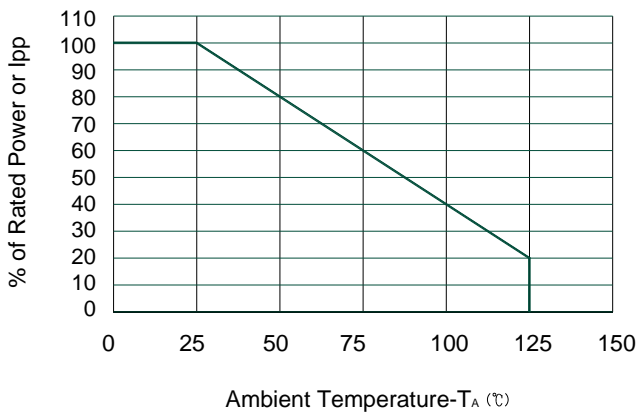
Typical electrical characterist applications



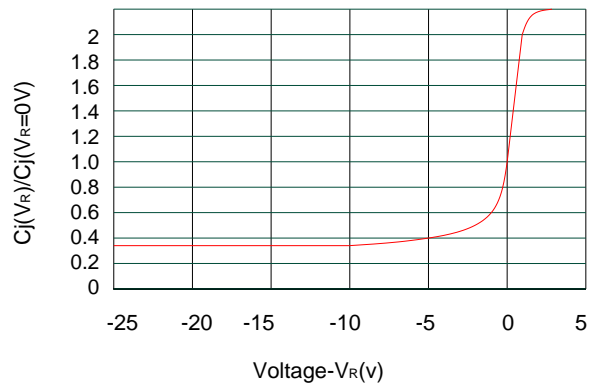
Pulse Waveform



Non-Repetitive Peak Pulse Power vs. Pulse Time



Power Derating Curve



Junction Capacitance vs. Reverse Voltage

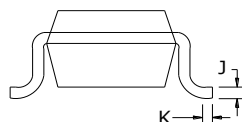
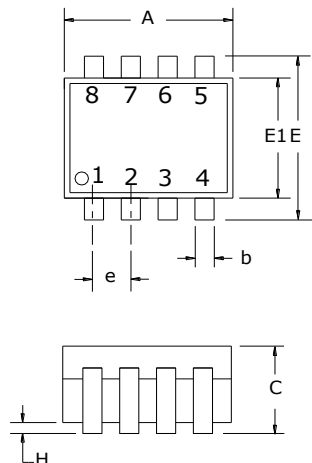
**Package Information**

**SOP-8**

**Mechanical Data**

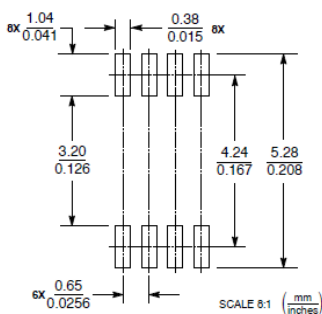
Case: SOP-8

Case Material: Molded Plastic. UL Flammability

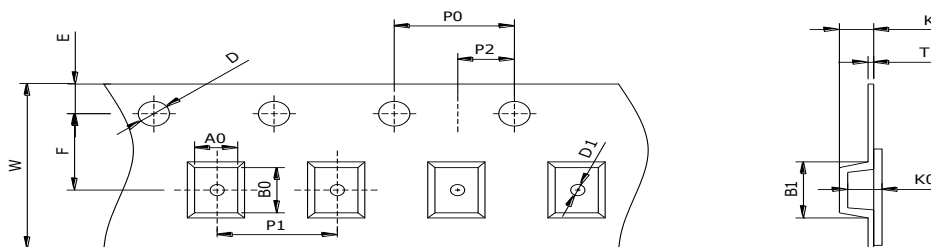


DIM	Millimeters		Inches	
	Min	Max	Min	Max
A	4.80	5.00	0.189	0.197
E	6.00(BSC)		0.236(BSC)	
E1	3.80	4.00	0.150	0.157
b	0.33	0.51	0.013	0.020
C	1.35	1.75	0.053	0.069
J	0.17	0.25	0.007	0.010
e	1.27(BSC)		0.05(BSC)	
K	0.40	1.27	0.016	0.050
H	0.10	0.25	0.004	0.010

**Recommended Pad outline**



**SOP-8 Reel Dim**



Package	Chip Size (mm)	Pocket Size B0xA0xK0(mm)	Tape Width	Reel Diameter	Quantity Per Reel	P0	P1
SOP-8	6.0x5.0x1.50	6.20x5.20x1.70	12mm	330mm(13")	2500	8mm	8mm
D0	D1	E	F	K	T	W	
1.5mm	1.5mm	1.75mm	5.0mm	1.55mm	0.20mm	12mm	